# Specifications

### Materials and Finish

Housing: Polyethersulphone (PES), glass-filled and Polyetherimide (PEI), glass-filled Contacts: Beryllium Copper (BeCu) Plating: Gold over Nickel

## Features

⇔ Open Top Handler type sockets for LGA / BGA / CSP packages

- Spring probe contacts in TH
- ➡ Depopulation versions available



### Socket / Handler Base (Cover Optional)

Part Number (Details)

IC275	-	048	49
Series No.			

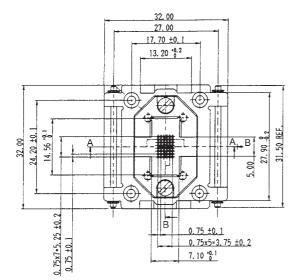
No. of Contact Pins

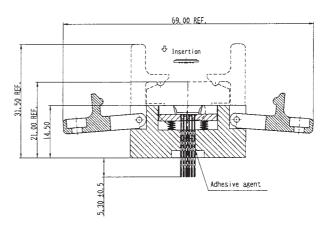
Design Number

# Ordering Procedure

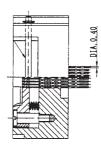
Note: Each Test Contactor Socket is custom built.

The customer must specify the number of contact pins, required pitch, all device parameters and any other special requirements. The final part number will be determined by Yamaichi.





Socket Cross-section



Part Number	Pin Count	Pitch	Grid Size	IC Body Size	Package Type
IC275-04833	48	0.75	6 x 8	6.0 x 8.0	CSP
IC275-04849	48	0.75	6 x 8	6.94 x 14.40	BGA
IC275-05450	48	0.75	6 x 8	6.5 x 6.5	BGA
IC275-38828	388	1.27	26 x 26	35.0 x 30.0	BGA

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#### Features

- ⇔ Open Top Handler type sockets for LGA / BGA / CSP packages
- Spring probe contacts in SMT
- $\Leftrightarrow$  Depopulation versions available

# Part Number (Details)

IC274 - 119 01

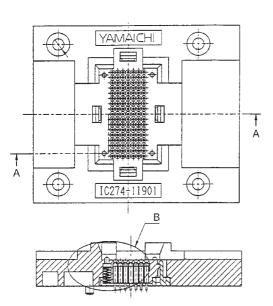
Series No.

No. of Contact Pins

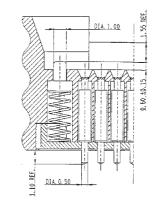
Design Number



#### Socket / Handler Base







Detail 'B'

### Socket / Handler Base with Cover

